

STARPOWER

SEMICONDUCTOR™

IGBT

GD1200SGL120C3S

Molding Type Module

1200V/1200A 1 in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and UPS.

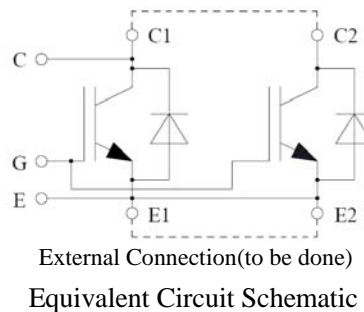


Features

- High short circuit capability, self limiting to $6 \cdot I_C$
- 10 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

Typical Applications

- AC inverter drives
- Switching mode power supplies
- Electronic welders



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Description	GD1200SGL120C3S	Units
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$	1900	A
		1200	
$I_{CM(1)}$	Pulsed Collector Current $t_p=1\text{ms}$	2400	A
I_F	Diode Continuous Forward Current	1200	A
I_{FM}	Diode Maximum Forward Current	2400	A
P_D	Maximum power Dissipation @ $T_j=175^{\circ}\text{C}$	8823	W
T_{SC}	Short Circuit Withstand Time @ $T_j=125^{\circ}\text{C}$	10	μs
T_j	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
I^2t -value, Diode	$V_R=0\text{V}$, $t=10\text{ms}$, $T_j=125^{\circ}\text{C}$	300	kA^2s
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V
Mounting Torque	Power Terminal Screw:M4	1.7 to 2.3	N.m
	Power Terminal Screw:M8	8.0 to 10	
	Mounting Screw:M6	4.25 to 5.75	N.m

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT $T_C=25^{\circ}\text{C}$ unless otherwise noted**Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{CES}	Collector-Emitter Breakdown Voltage	$T_j=25^{\circ}\text{C}$	1200			V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}$, $V_{GE}=0\text{V}$, $T_j=25^{\circ}\text{C}$			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}$, $V_{CE}=0\text{V}$, $T_j=25^{\circ}\text{C}$			800	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=48.0\text{mA}$, $V_{CE}=V_{GE}$, $T_j=25^{\circ}\text{C}$	5.0	6.5	7.0	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=1200\text{A}$, $V_{GE}=15\text{V}$, $T_j=25^{\circ}\text{C}$		1.9		V
		$I_C=1200\text{A}$, $V_{GE}=15\text{V}$, $T_j=125^{\circ}\text{C}$		2.1		

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
R_{Gint}	Internal gate resistor	$T_j=25^\circ\text{C}$		1.2		Ω
Q_{ge}	Gate charge	$I_C=1200\text{A}, V_{CE}=600\text{V},$ $V_{GE}=-15\dots+15\text{V}$		12.5		μC
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=1200\text{A},$ $R_G=0.82\Omega, V_{GE} = \pm 15\text{V},$ $T_j=25^\circ\text{C}$		790		ns
t_r	Rise Time			170		ns
$t_{d(off)}$	Turn-Off Delay Time			1350		ns
t_f	Fall Time			180		ns
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=1200\text{A},$ $R_G=0.82\Omega, V_{GE} = \pm 15\text{V},$ $T_j=125^\circ\text{C}$		850		ns
t_r	Rise Time			170		ns
$t_{d(off)}$	Turn-Off Delay Time			1500		ns
t_f	Fall Time			220		ns
E_{on}	Turn-On Switching Loss			155		mJ
E_{off}	Turn-Off Switching Loss			190		mJ
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=1\text{MHz},$ $V_{GE}=0\text{V}$		92.0		nF
C_{oes}	Output Capacitance			8.40		nF
C_{res}	Reverse Transfer Capacitance			6.10		nF
I_{SC}	SC Data	$t_{sc} \leq 10\mu\text{s}, V_{GE}=15\text{V},$ $T_j=125^\circ\text{C}, V_{CC}=900\text{V},$ $V_{CEM} \leq 1200\text{V}$		7000		A
L_{CE}	Stray Inductance			15		nH
$R_{CC'+EE'}$	Module lead resistance, terminal to chip	$T_C=25^\circ\text{C}, \text{per switch}$		0.10		m Ω

Electrical Characteristics of Diode $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_F	Diode Forward Voltage	$I_F=1200\text{A}$	$T_j=25^\circ\text{C}$		1.9	V
			$T_j=125^\circ\text{C}$		2.1	
Q_r	Diode Reverse Recovery Charge	$I_F=1200\text{A},$ $V_R=600\text{V},$ $di/dt=-6800\text{A}/\mu\text{s},$ $V_{GE}=-15\text{V}$	$T_j=25^\circ\text{C}$		110	μC
			$T_j=125^\circ\text{C}$		220	
I_{RM}	Diode Peak Reverse Recovery Current		$T_j=25^\circ\text{C}$		760	A
			$T_j=125^\circ\text{C}$		990	
E_{rec}	Reverse Recovery Energy		$T_j=25^\circ\text{C}$		47	mJ
			$T_j=125^\circ\text{C}$		82	

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case (IGBT Part, per Module)		0.017	K/W
$R_{\theta JC}$	Junction-to-Case (Diode Part, per Module)		0.025	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied, per Module)	0.006		K/W
Weight	Weight of Module	1500		g

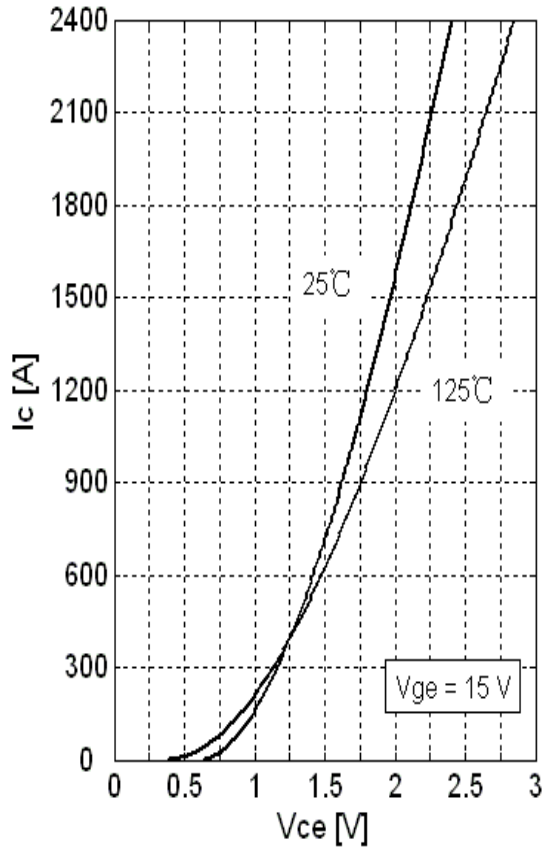


Fig 1. Typical IGBT Output Characteristics

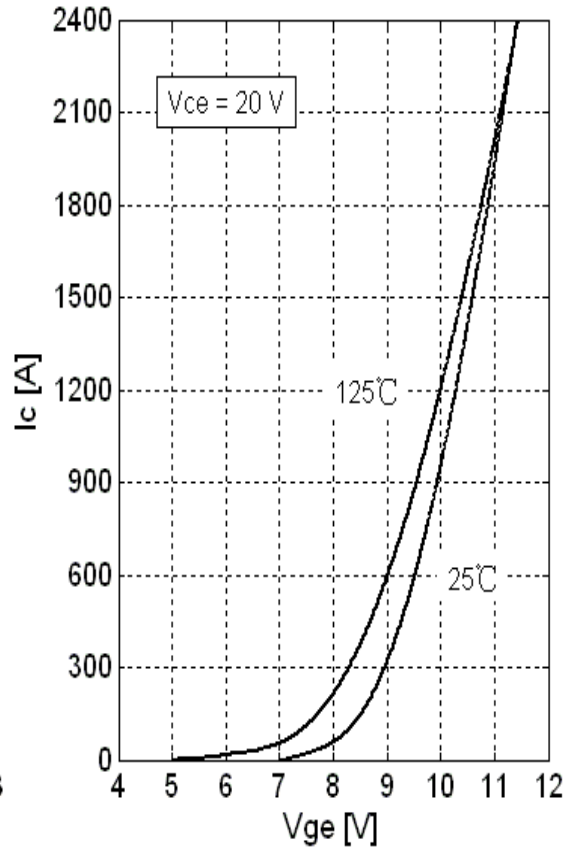


Fig 2. Typical IGBT Transfer Characteristics

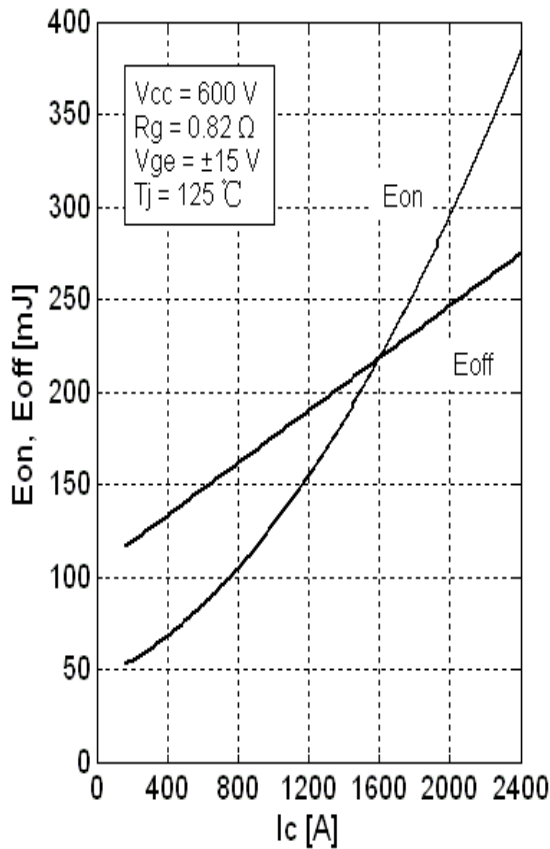


Fig 3. IGBT Switching Loss vs Collector Current

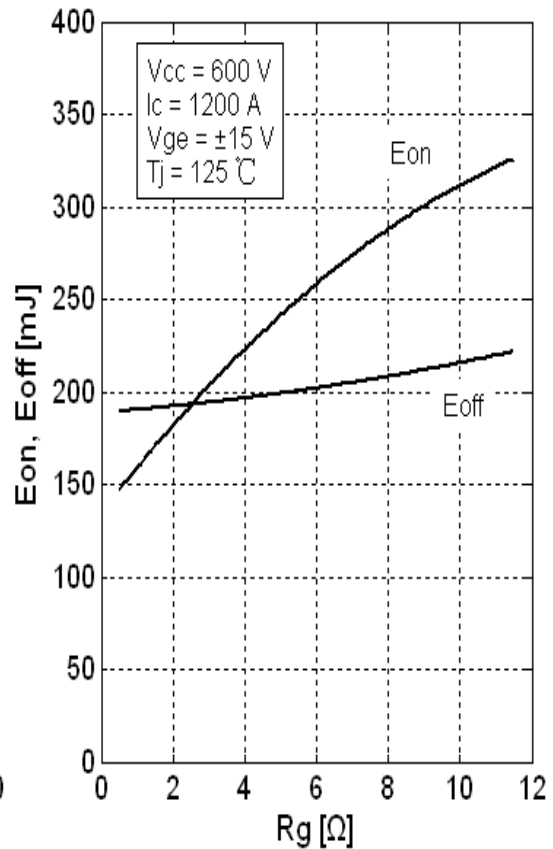


Fig 4. IGBT Switching Loss vs Gate Resistor

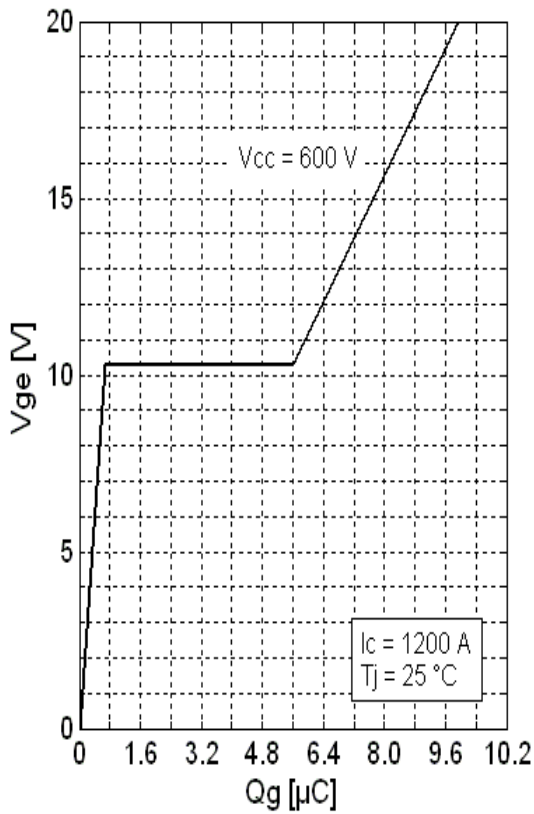


Fig 5. IGBT Gate Charge Characteristics

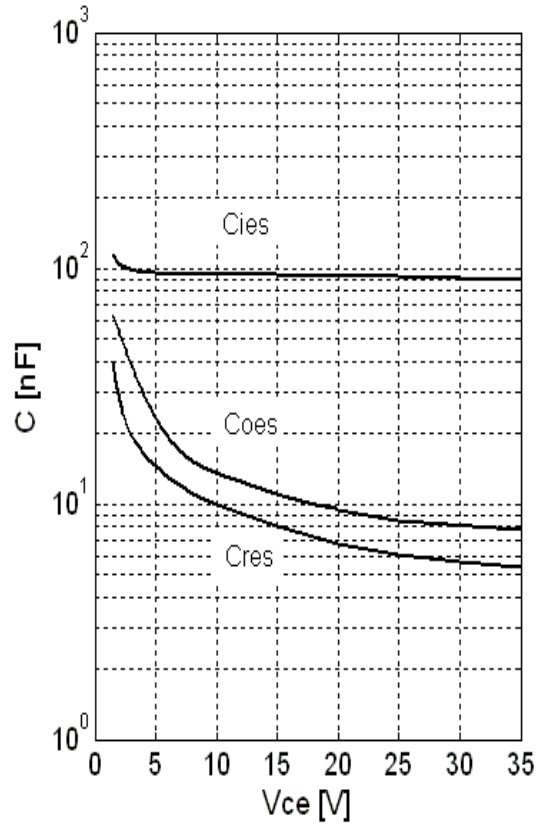


Fig 6. Typical IGBT Capacitance vs Collector-Emitter Voltage

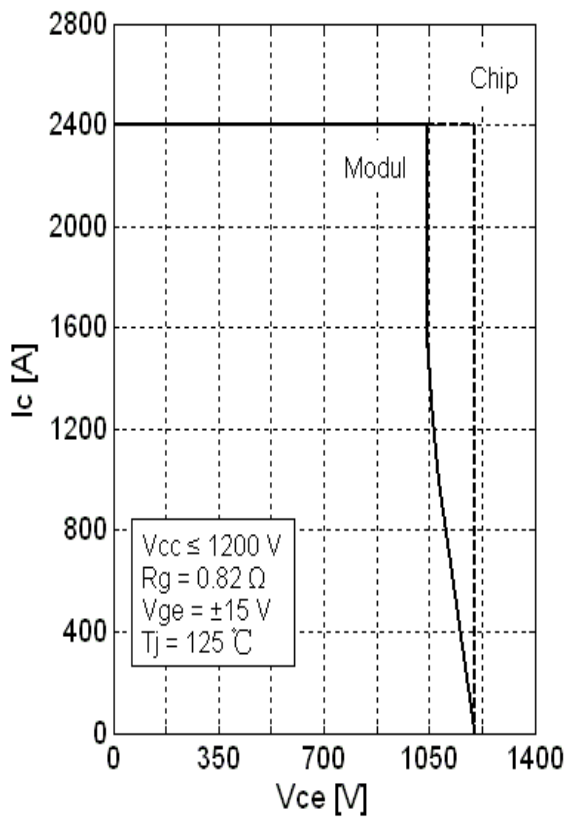


Fig 7. IGBT Turn-off Safe Operating Area (RBSOA)

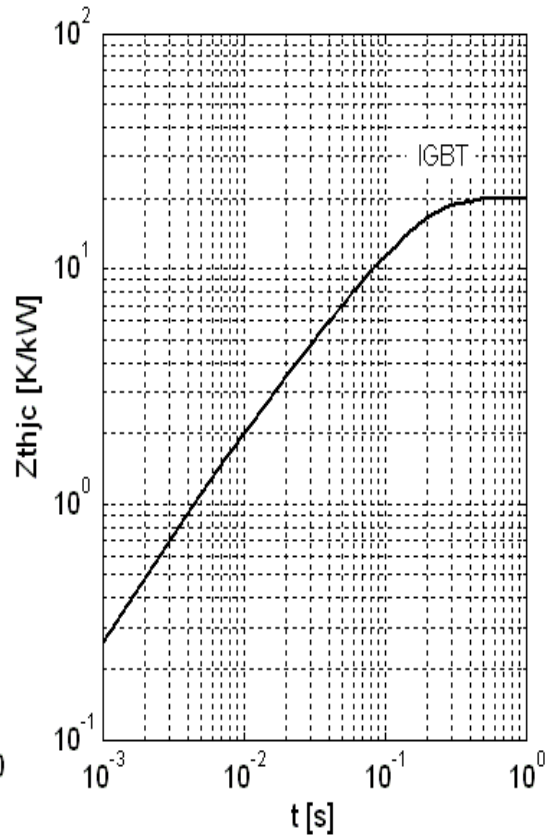


Fig 8. IGBT Transient Thermal Impedance

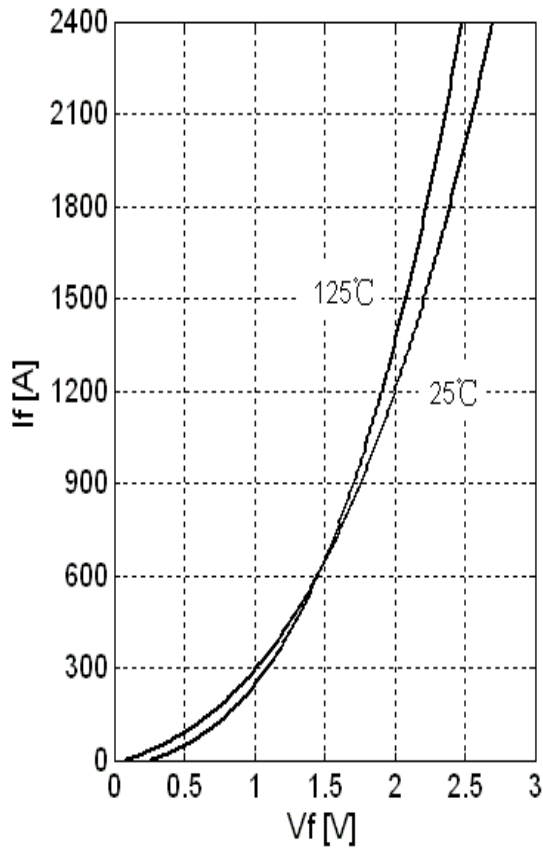


Fig 9. Typical Diode Forward Characteristics

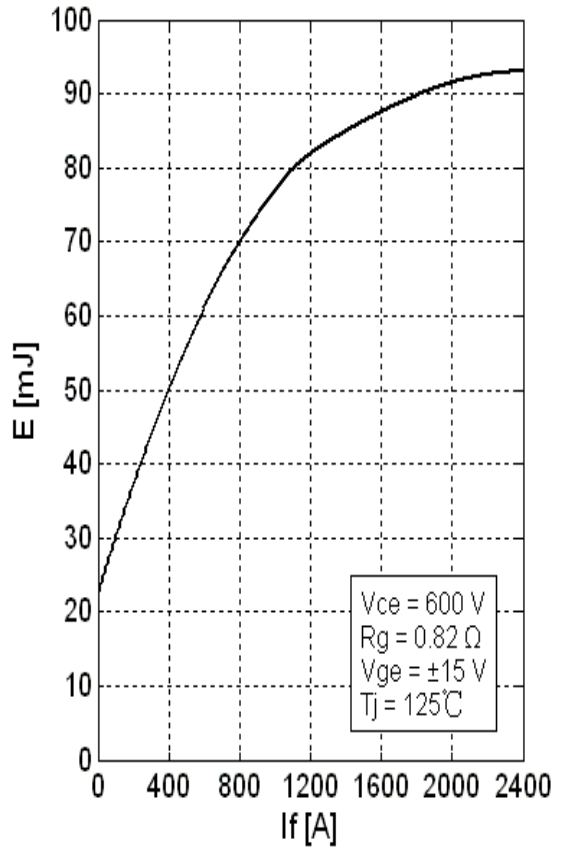


Fig 10. Diode Switching Loss vs Collector Current

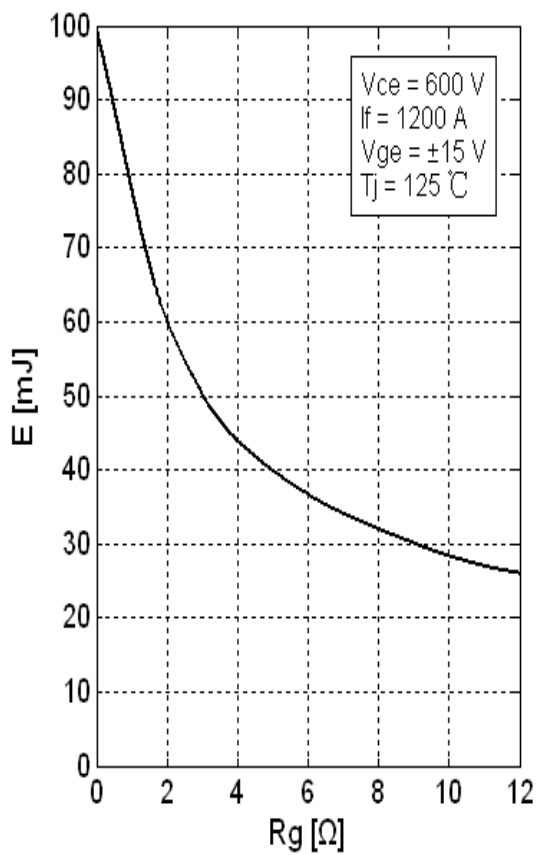


Fig 11. Diode Switching Loss vs Gate Resistor

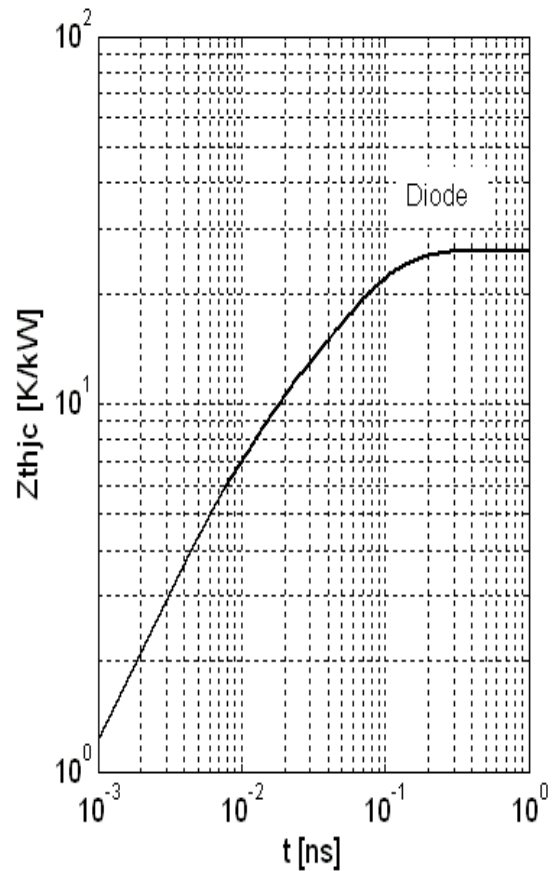
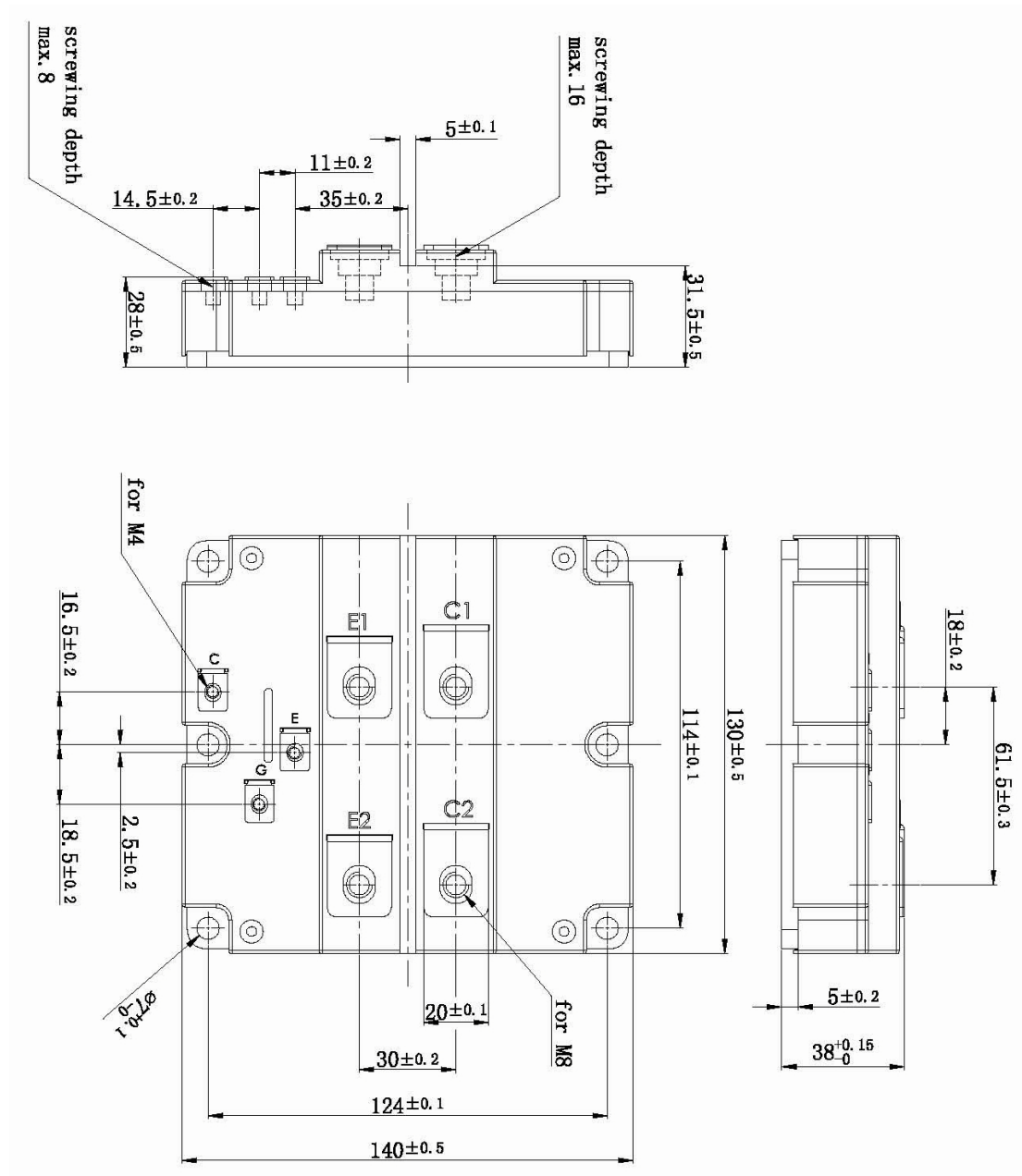


Fig 12. Diode Transient Thermal Impedance

Package Dimension

Dimensions in Millimeters



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